

## Description

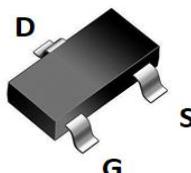
### N-channel Advanced Mode Power MOSFET

#### Features

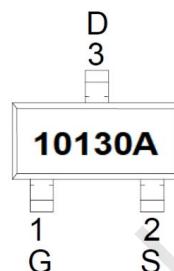
- 100V, 3A
- $R_{DS(ON)}$  Typ= 95mΩ @  $V_{GS}$  = 10V
- $R_{DS(ON)}$  Typ=135mΩ @  $V_{GS}$  =4.5V
- Advanced Split Gate Trench Technology
- Excellent  $R_{DS(ON)}$  and Low Gate Charge
- Lead Free

#### Applications

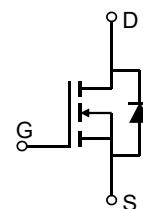
- DC/DC Converter
- LED Backlighting
- Motor Control



SOT-23



Marking and Pin Assignment



Schematic Diagram

#### Package Marking and Ordering Information

Device Marking	Device	Outline	Package	Reel Size	Reel(pcs)	Per Carton (pcs)
10130A	CRMLGL10130A	TAPING	SOT-23	7"	3000	120000

#### Absolute Maximum Ratings (@ $T_J$ = 25°C unless otherwise specified)

Symbol	Parameter	Value	Units
$V_{DS}$	Drain-to-Source Voltage	100	V
$V_{GS}$	Gate-to-Source Voltage	$\pm 20$	V
$I_D$	Continuous Drain Current T <sub>A</sub> = 25°C	3	A
		2.2	
$I_{DM}$	Pulsed Drain Current <sup>(1)</sup>	12	A
$P_D$	Power Dissipation T <sub>A</sub> = 25°C	3.1	W
$R_{\theta JA}$	Thermal Resistance, Junction to Ambient <sup>(2)</sup>	40.3	°C/W
$T_J, T_{STG}$	Junction & Storage Temperature Range	-55 to 150	°C

**Electrical Characteristics (T<sub>J</sub> = 25°C unless otherwise specified)**

Symbol	Parameter	Conditions	Min.	Typ.	Max.	Unit
<b>Off Characteristics</b>						
V <sub>(BR)DSS</sub>	Drain-Source Breakdown Voltage	I <sub>D</sub> = 250μA, V <sub>GS</sub> = 0V	100	-	-	V
I <sub>DSS</sub>	Zero Gate Voltage Drain Current	V <sub>DS</sub> = 100V, V <sub>GS</sub> = 0V	-	-	1.0	μA
I <sub>GSS</sub>	Gate-Body Leakage Current	V <sub>DS</sub> = 0V, V <sub>GS</sub> = ±20V	-	-	±100	nA
<b>On Characteristics</b>						
V <sub>GS(th)</sub>	Gate Threshold Voltage	V <sub>DS</sub> = V <sub>GS</sub> , I <sub>D</sub> = 250μA	1.0	1.65	2.5	V
R <sub>DS(ON)</sub>	Static Drain-Source ON-Resistance <sup>(3)</sup>	V <sub>GS</sub> = 10V, I <sub>D</sub> = 3A	-	95	130	mΩ
		V <sub>GS</sub> = 4.5V, I <sub>D</sub> = 1A	-	135	190	mΩ
<b>Dynamic Characteristics</b>						
C <sub>iss</sub>	Input Capacitance	V <sub>GS</sub> = 0V, V <sub>DS</sub> = 50V, f = 1MHz	-	200	-	pF
C <sub>oss</sub>	Output Capacitance		-	30	-	pF
C <sub>rss</sub>	Reverse Transfer Capacitance		-	3	-	pF
Q <sub>g</sub>	Total Gate Charge	V <sub>GS</sub> = 0 to 10V V <sub>DS</sub> = 50V, I <sub>D</sub> = 3A	-	4	-	nC
Q <sub>gs</sub>	Gate Source Charge		-	0.9	-	nC
Q <sub>gd</sub>	Gate Drain("Miller") Charge		-	1.1	-	nC
<b>Switching Characteristics</b>						
t <sub>d(on)</sub>	Turn-On DelayTime	V <sub>GS</sub> = 10V, V <sub>DD</sub> = 50V I <sub>D</sub> = 3A, R <sub>GEN</sub> = 3Ω	-	13	-	ns
t <sub>r</sub>	Turn-On Rise Time		-	19	-	ns
t <sub>d(off)</sub>	Turn-Off DelayTime		-	20	-	ns
t <sub>f</sub>	Turn-Off Fall Time		-	28	-	ns
<b>Drain-Source Diode Characteristics and Max Ratings</b>						
I <sub>S</sub>	Maximum Continuous Drain to Source Diode Forward Current	-	-	3	A	
I <sub>SM</sub>	Maximum Pulsed Drain to Source Diode Forward Current	-	-	12	A	
V <sub>SD</sub>	Drain to Source Diode Forward Voltage	V <sub>GS</sub> = 0V, I <sub>S</sub> = 3A	-	-	1.2	V

Notes:

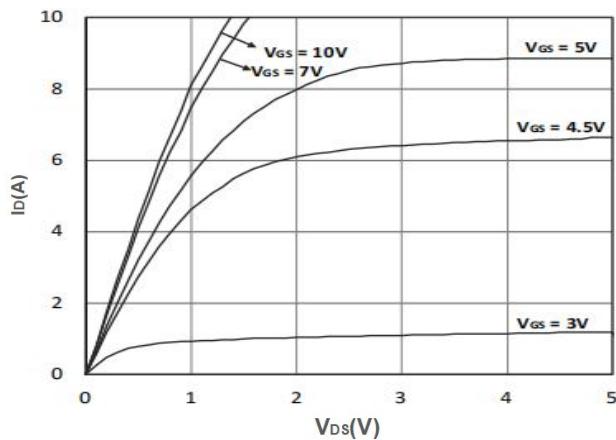
1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature.

2. R<sub>θJA</sub> is measured with the device mounted on a 1inch<sup>2</sup> pad of 2oz copper FR4 PCB

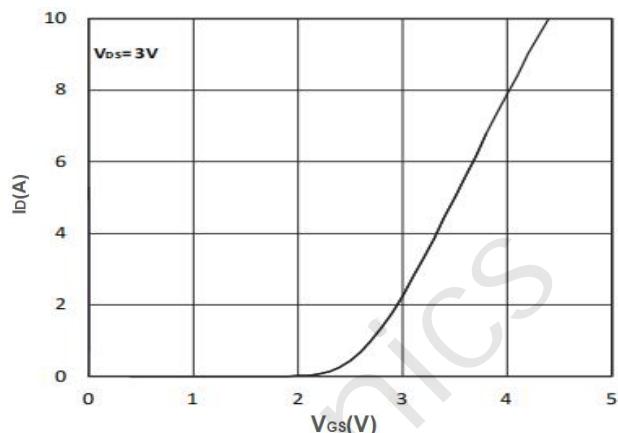
3. Pulse Test: Pulse Width≤300μs, Duty Cycle≤0.5%.

## Typical Performance Characteristics

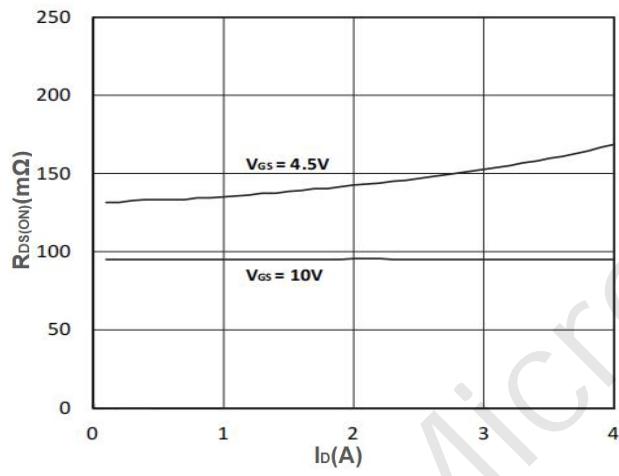
**Figure 1: Output Characteristics**



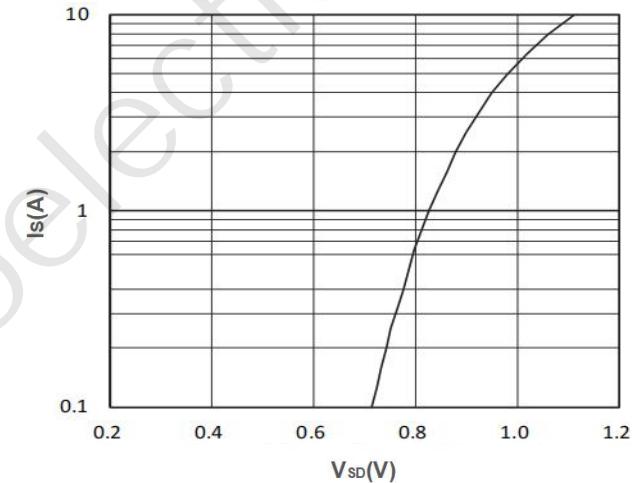
**Figure 2: Typical Transfer Characteristics**



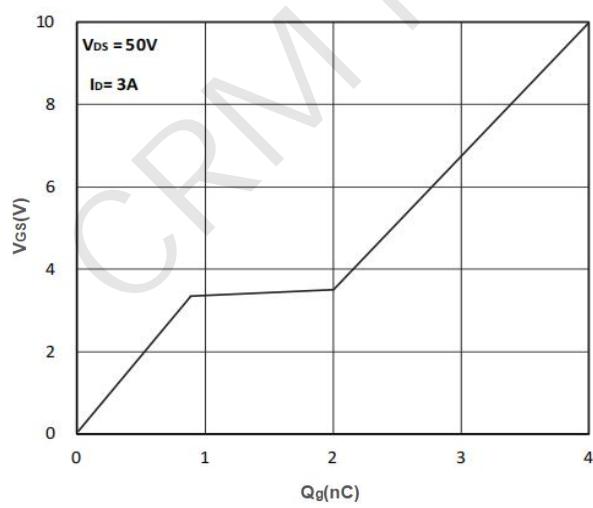
**Figure 3: On-resistance vs. Drain Current**



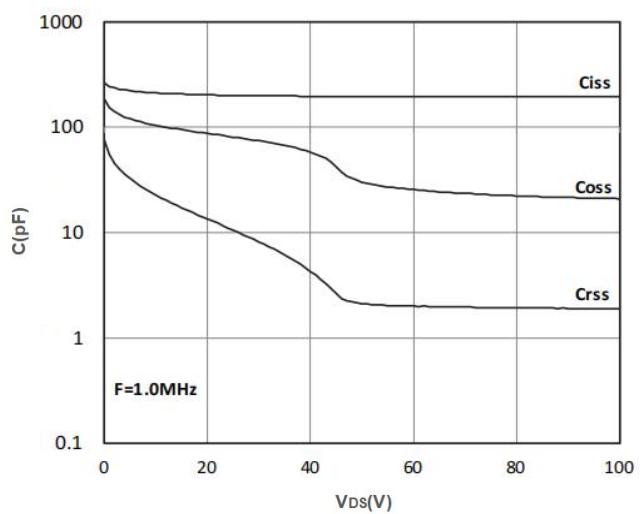
**Figure 4: Body Diode Characteristics**



**Figure 5: Gate Charge Characteristics**

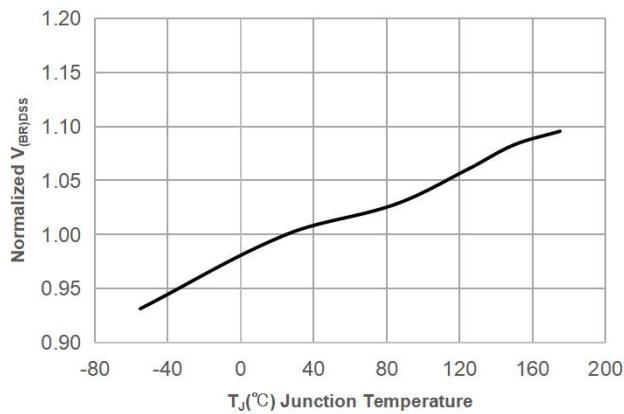


**Figure 6: Capacitance Characteristics**

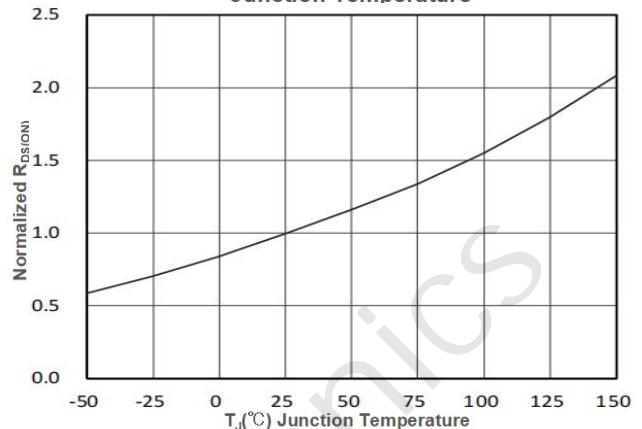


## Typical Performance Characteristics

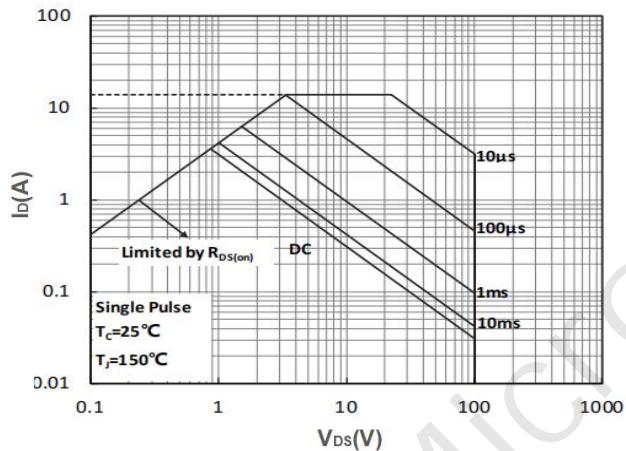
**Figure 7: Normalized Breakdown voltage vs. Junction Temperature**



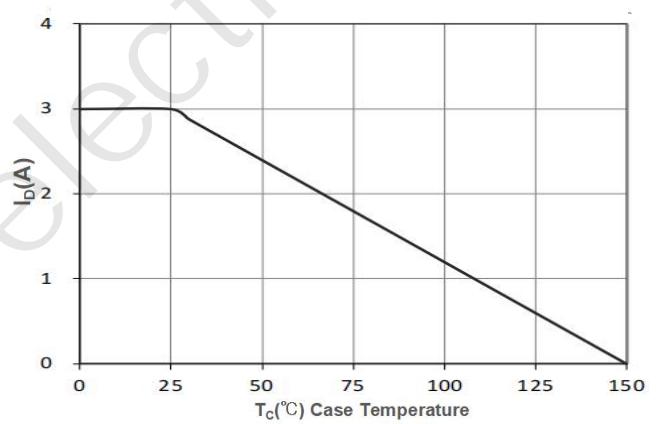
**Figure 8: Normalized on Resistance vs. Junction Temperature**



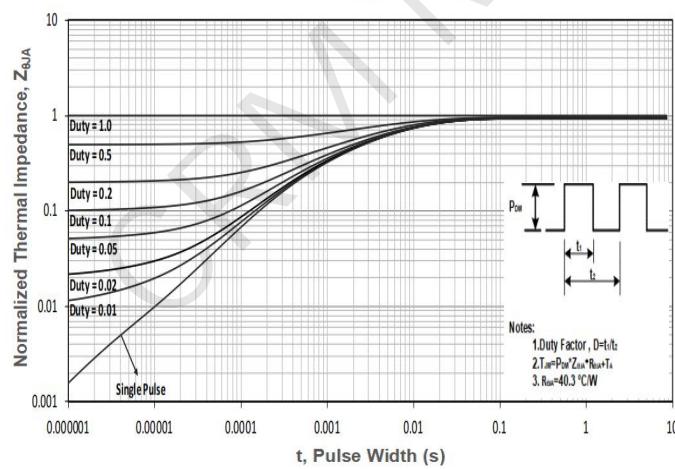
**Figure 9: Maximum Safe Operating Area**



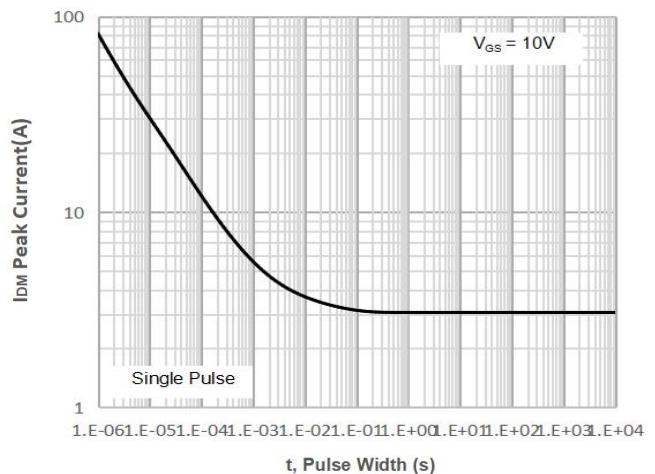
**Figure 10: Maximum Continuous Drain Current vs. Case Temperature**



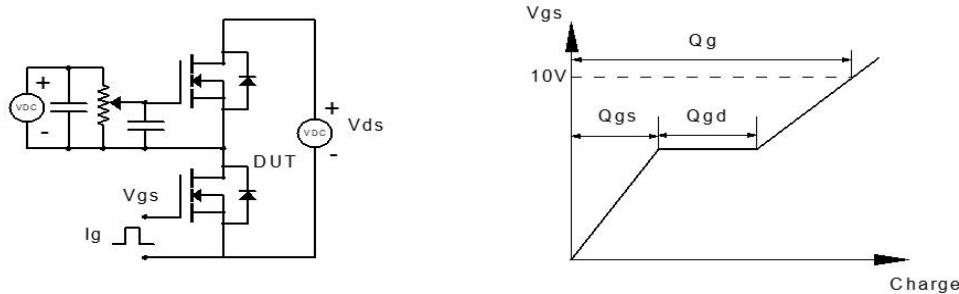
**Figure 11: Normalized Maximum Transient Thermal Impedance**



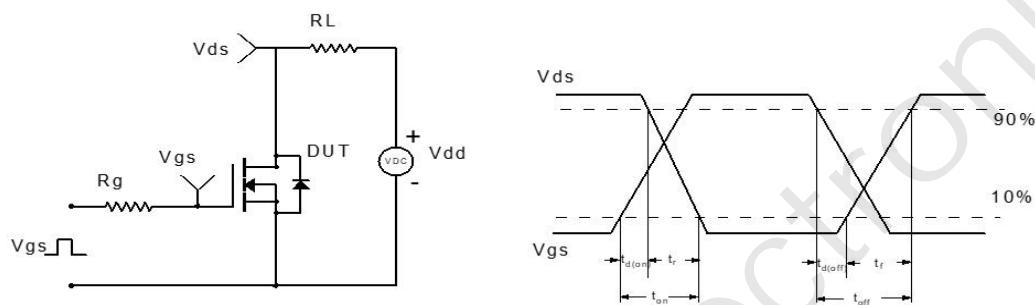
**Figure 12: Peak Current Capacity**



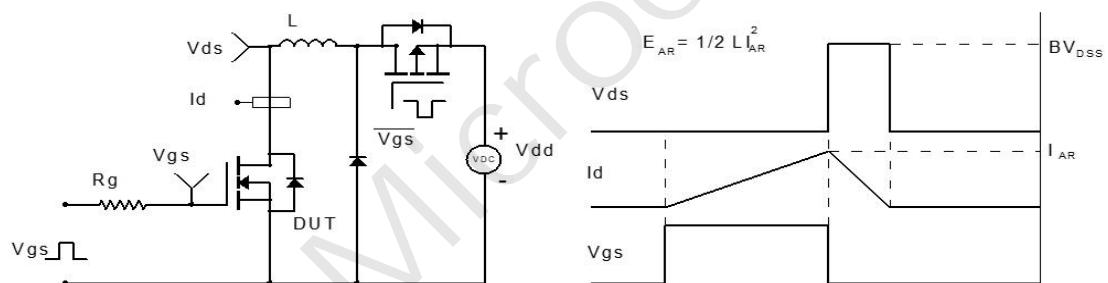
## Test Circuit



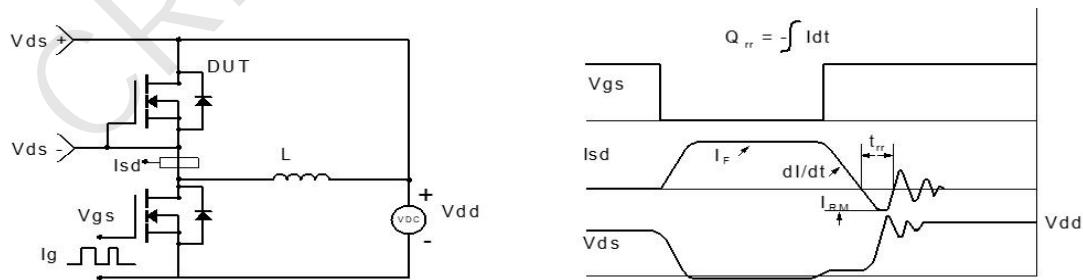
**Figure 1: Gate Charge Test Circuit & Waveform**



**Figure 2: Resistive Switching Test Circuit & Waveform**

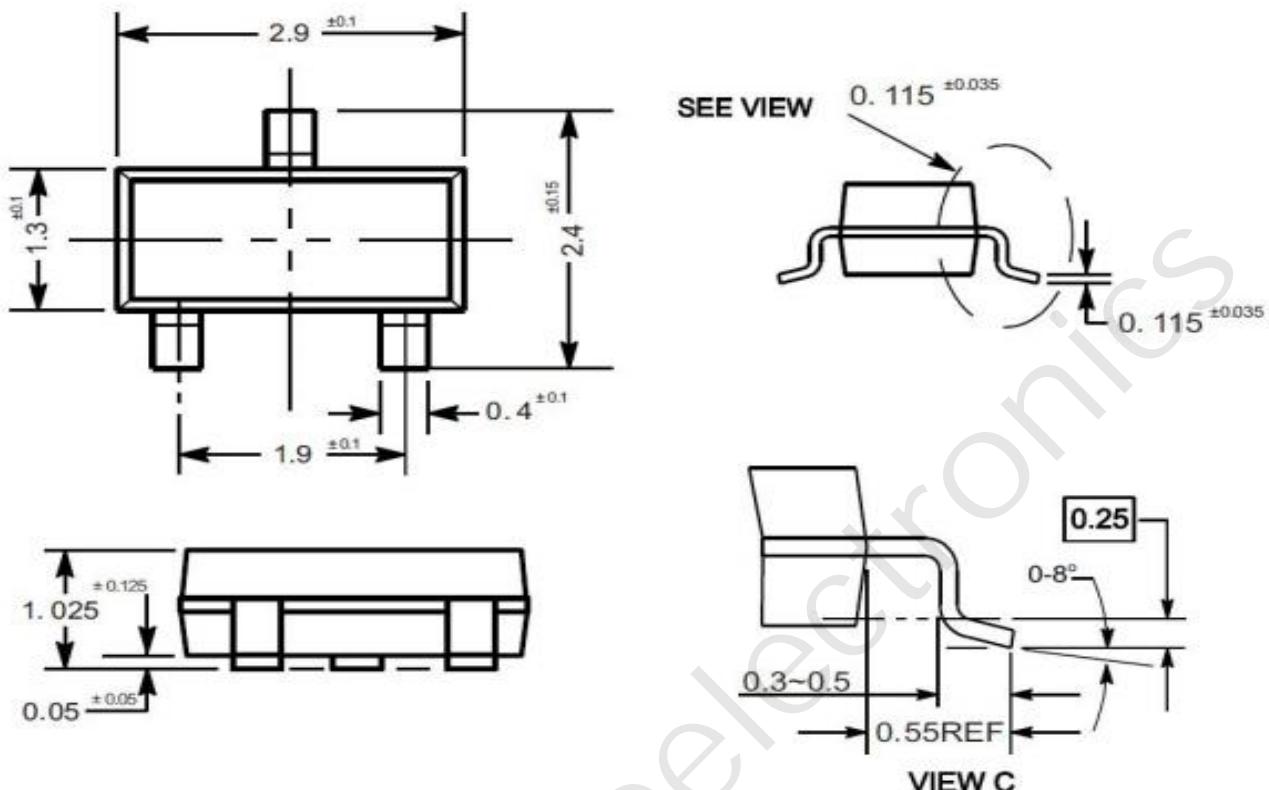


**Figure 3: Unclamped Inductive Switching Test Circuit & Waveform**



**Figure 4: Diode Recovery Test Circuit & Waveform**

## Package Mechanical Data(SOT-23)



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